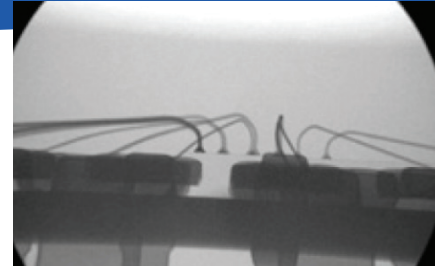
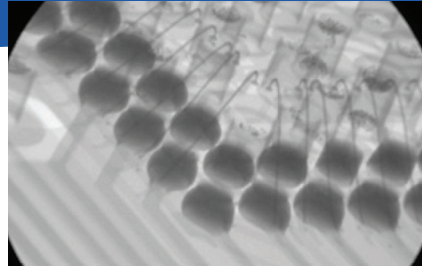
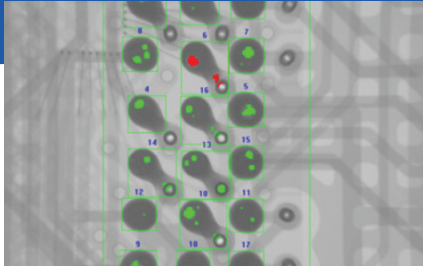


Post-Processing Software

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Vital to quality control, NAI Industrial software allows manufacturers to find contamination, scratches, cracks, blemishes, gaps, pits and other production flaws. Post-processing software can detect defects invisible to the human eye – faster and more accurately.

We offer several user-friendly software packages to meet a variety of applications for a wide range of industries. Choose from one of our three software packages or let us put together a customized package to fit your unique needs. Contact Josh Hunt at 805.383.2214 or jhunt@NAImaging.com for more information.

Standard Software Features

- Image capturing and saving (.jpg, .bmp)
- Live image frame averaging
- Post capture image enhancements:
 - *Brightness and contrast adjustments*
 - *Image filters (sharpen, psuedo color, negative)*
- Point-to-point distance measurement tool
- Measurement calibration (inches, mm, pixels)
- Image annotation tool:
 - *On screen text tool*
 - *Arrow drawing*
 - *Line, circular or rectangular shape drawing*
 - *Angle measurement tool*
 - *Rectangle measurement tool*
 - *PTH (plated thru hole) measurement tool*
- Video recording tool:
 - *Record and save continuous inspection motion program*
- Image rotation/flip tool (allows user to rotate and flip images 90, 180, 270 degrees plus horizontal and vertical image flip)

Analysis Software Features

Analysis Software Package includes:

- BGA measurement algorithm tools
 - *Ball size:*
 - *Ball area*
 - *Ball diameter*
 - *Ball roundness*
 - *Percent void*
 - *Pass fail criteria*
 - *Image reporting*
- QFN measurement algorithm tools:
 - *Joint area*
 - *Percent void*
 - *Pass/fail criteria*

Advanced Analysis Features

Advanced Analysis Software Package includes:

- Semiconductor measurement algorithm tools:
 - *Bond wire sweep*
 - *Die attach void measurement*
 - *Pass/fail criteria*
 - *Drill offset measurement*
 - *Center to center offset (X & Y distance)*
- 3D image rendering:
 - *Three dimensional image reconstruction*
 - *Black/white and color*
 - *Image rotation and reposition*
- Histogram:
 - *Selectable area histogram measurement*
- Measurement ROI for system calibration:
 - *Use to confirm system imaging performance*